

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Reissue Patent Application:

Applicant : Gurtej S. Sandhu
 Assignee: : Micron Technology, Inc.
 Filed : December 28, 2001
 For : METHOD AND APPARATUS FOR ENDPOINTING MECHANICAL AND
 CHEMICAL-MECHANICAL POLISHING OF SUBSTRATES
 Docket No. : 500042.02

Corresponding Issued U.S. Patent:

Patent No. : 6,007,408
 Issued : December 28, 1999
 Application No. : 08/917,665
 Filing Date : August 21, 1997
 Examiner : George Nguyen
 Art Unit : 3723

BOX REISSUE
 Commissioner for Patents
 Washington, DC 20231

REISSUE DECLARATION

As below-named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below.

I believe that I am the original, first and sole inventor of the innovative subject matter described and claimed in the application for reissue of U.S. Patent No. 6,007,408, which is entitled "METHOD AND APPARATUS FOR ENDPOINTING MECHANICAL AND CHEMICAL-MECHANICAL POLISHING OF SUBSTRATES."

I hereby state that I have reviewed and understand the contents of the above-identified U.S. reissue patent application, INCLUDING BOTH THE ORIGINAL CLAIMS AND THE NEW CLAIMS PRESENTED IN THE ENCLOSED PRELIMINARY AMENDMENT.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulation, § 1.56(a).

I believe the above-identified original patent 6,007,408 to be partly inoperative, by reason of the patentees claiming less than we had a right to claim. For example, claim 1 of the

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'408 patent is limited to a method for stopping polishing of a substrate at a desired endpoint comprising sensing the temperature of byproducts produced from polishing the substrate. Therefore, I am implementing my right to claim at least methods comprising sensing of a characteristic other than temperature to determine the polishing endpoint, and also methods comprising sensing of characteristics of materials other than the byproducts produced during the polishing of the substrate. This error arose without any deceptive intention on my part.

Accordingly, the enclosed Preliminary Amendment presents additional independent method claims that are the error noted above. These independent claims have been newly drafted to more particularly point out and distinctly claim the invention. The Preliminary Amendment also presents additional dependent claims. I believe that my invention is at least as broad as these claims.

I do not know and do not believe that the claimed invention was ever known or used in the United States of America before my invention thereof.

I do not know and do not believe that the claimed invention was ever patented or described in any printed publication in any country before my invention thereof.

I do not know and do not believe that the claimed invention was ever patented or described in any printed publication in any country more than one year prior to the filing date of the original U.S. application.

I do not know and do not believe that the claimed invention was ever in public use or on sale in the United States of America more than one year prior to the filing date of the original U.S. application.

I hereby declare that all statements made of my knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements are made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and may also jeopardize the validity of the application or any patent issued thereon.

Inventor: Gurtej S. Sandhu

Date

Residence and Mailing Address: 2964 East Parkriver Drive, Boise, Idaho 83706

Citizenship: United States of America

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OFFER TO SURRENDER THE ORIGINAL PATENT

Sir:

Michael L. Lynch, Chief Patent Counsel of the Assignee of the entire interest in U.S. Letters Patent No. 6,007,408 which is entitled METHOD AND APPARATUS FOR ENDPOINTING MECHANICAL AND CHEMICAL-MECHANICAL POLISHING OF SUBSTRATES and issued on December 28, 1999, to Micron Technology, Inc., hereby offers to surrender said Letters Patent.

Micron Technology, Inc.

Date

By: _____

Michael L. Lynch
Chief Patent Counsel

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ASSENT OF ASSIGNEE

The undersigned, Micron Technology, Inc. (hereinafter "Micron"), a corporation of the State of Delaware having a place of business at 8000 South Federal Way, Boise, Idaho 83716, declares that it is the assignee of the entire right, title, and interest in the above-identified U.S. Patent No. 6,007,408. Documentary evidence of chain of title from the original owner to Micron has been filed with and recorded by the United States Patent Office at Reel 8781, Frame 0755. The evidentiary documents referred to in the instant Assent of Assignee have been reviewed by the undersigned and it is certified that, to the best of Micron's knowledge and belief, title is in Micron.

The undersigned Assignee hereby assents to the reissue application.

Date _____

By: Michael L. Lynch
Chief Patent Counsel